

# **International Conference on Silicon Carbide and Related Materials 2022**

Selected peer-reviewed extended articles  
based on abstracts presented at the  
19<sup>th</sup> International Conference on  
Silicon Carbide and Related Materials  
(ICSCRM) 2022  
11-16 September 2022, Davos, Switzerland

*Edited by*

**Juraj Marek, Gregor Pobegen and Ulrike Grossner**

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Seestrasse 24c  
CH-8806 Baech  
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<https://www.scientific.net>

*ISBN 978-3-0364-0167-6*

Full text available online at <https://www.scientific.net>

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